

LISTING OF CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) An electro-optical modulator, comprising:
a ~~modulator~~ Lithium Niobate chip having a low impedance and an RF electrode;
and
a microwave input chip coupled to the ~~modulator~~ Lithium Niobate chip, the microwave input chip having a thin film resistor for connecting an RF connector to the RF electrode of the ~~modular~~ Lithium Niobate chip, wherein the microwave input chip is configured to increase the total input impedance of the modulator.
2. (Cancelled)
3. (Previously Presented) The electro-optical modulator of Claim 1, further comprising a microstrip line in the microwave input chip, the thin film resistor being placed in the microstrip line.
4. (Previously Presented) The electro-optical modulator of Claim 3, wherein the microstrip line is a straight line.
5. (Previously Presented) The electro-optical modulator of Claim 1, further comprising a coplanar waveguide in the microwave input chip, the thin film resistor being placed in the coplanar waveguide.
6. (Previously Presented) The electro-optical modulator of Claim 3, wherein the microstrip line is curved.

7. (Previously Presented) The electro-optical modulator of Claim 1, further comprising a plurality of bondings for coupling the microwave input chip to the modulator chip.
8. (Cancelled)
9. (Original) The electro-optical modulator of Claim 1, wherein the microwave input chip is manufactured with a substrate of Alumina, Gallium Arsenide, Aluminum Nitride or other type of substrates commonly used for microwave applications.
10. (Currently Amended) An electro-optical modulator, comprising:
a ~~modulator~~ Lithium Niobate chip having a low impedance and an RF electrode;
and
a microwave input chip coupled to the ~~modulator~~ Lithium Niobate chip, the microwave input chip having a resistor member with a low impedance for increasing the total input impedance of the modulator, wherein the resistor member connects an RF connector to the RF electrode of the ~~modulator~~ Lithium Niobate chip.
11. (Previously Presented) The electro-optical modulator of Claim 10, wherein the resistor member comprises a thin film resistor.
12. (Previously Presented) The electro-optical modulator of Claim 10, wherein the resistor member comprises a lumped resistance.
13. (Cancelled)
14. (Previously Presented) The electro-optical modulator of Claim 10, further comprising a microstrip line or coplanar line in the microwave input chip, the resistor member being placed in the microstrip line.

15. (Previously Presented) The electro-optical modulator of Claim 14, wherein the microstrip line is a straight line.
16. (Previously Presented) The electro-optical modulator of Claim 10, further comprising a coplanar waveguide in the microwave input chip, the resistor member being placed in the coplanar waveguide.
17. (Previously Presented) The electro-optical modulator of Claim 14, wherein the microstrip line is curved.
18. (Previously Presented) The electro-optical modulator of Claim 10, further comprising a plurality of bondings for coupling the microwave input chip to the modulator chip.
19. (Cancelled)
20. (Original) The electro-optical modulator of Claim 10, wherein the microwave input chip is manufactured with a substrate of Alumina, Gallium Arsenide, Aluminum Nitride or other type of substrates commonly used for microwave applications.
21. (Previously Presented) The electro-optical modulator of Claim 1, wherein the thin film resistor has a resistance between 1-10 Ohms.
22. (Previously Presented) The electro-optical modulator of Claim 10, wherein the resistor member has a resistance between 1-10 Ohms.